

L4 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2000 ACS
 AN 1984:572633 CA
 DN 101:172633
 TI Electric cable with crosslinked polyethylene insulation
 PA Sumitomo Electric Industries, Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 3 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC H01B003-44; H01B007-00
 CC 38-3 (Plastics Fabrication and Uses)
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 59099611	A2	19840608	JP 1982-210090	19821130 <--
AB	<p>The cable uses low-d. polyethylene [9002-88-4] for which the ratio of wt.-av. mol. wt. to no.-av. mol. wt. is .ltoreq.5. Preferably, the polymer is crosslinked by a dry method and the insulation thickness is .gtoreq.7 mm, and there may be a metallic waterproof layer. The cable provides much improved weatherability. Thus, low-d. polyethylene (ratio 4) was mixed with 2,5-dimethyl-2,5-bis(tert-butylperoxy)hexane [78-63-7], extruded to form the insulator layer of the cable, and heated by IR irradsn. for crosslinking. Comparative tests showed increased durability.</p>				

===== WPI =====

- TI - Near infrared radiation-setting foam resin compsn. - contains addn. polymerisable ethylenically unsatd. cpd., initiator and hollow filler(s)
- AB - J06192459 The compsn. contains an addn.-polymerisable ethylenically unsatd. cpd., a near infrared radiation polymerisation initiator and hollow filler(s) or thermally expansive microcapsules.
- The addn. polymerisable ethylenically unsatd. cpd. is a (meth)acrylic ester of monohydric or polyhydric alcohol or a methacrylic ester. The hollow filler(s) of up to 300 microns grain size comprise(s) silica, glass, carbon or alumina. The thermally expansive microcapsules composed of vinylidene chloride-acrylonitrile copolymer include a low b.pt. solvent such as isobutylene.
- USE/ADVANTAGE - The compsn. can be hardened in a short time by irradiation with near infrared. The foamed hardened resin compsn. is used as an adiabatic coating material for refrigerator, an insulator for the wall of a house, a gasket or a sealant. (Dwg.0/0)
- PN - JP6192459 A 19940712 DW199432 C08J9/14 006pp
- PR - JP19920357728 19921225
- PA - (TOKT) TOKYO THREE BOND CO LTD
- MC - A02-A09 A04-D03 A04-E07 A04-F06E A08-R01 A12-S04B G02-A05 G04-B01 G04-B02
- DC - A14 A88 A93 G02 G04 P42
- IC - B05D3/06 ;C08J9/14 ;C09D4/00 ;C09K3/10
- AN - 1994-260634 [32]

===== PAJ =====

- TI - NEAR-INFRARED-CURING EXPANDABLE RESIN COMPOSITION
- AB - PURPOSE:To obtain a composition which can give a cured thick product upon irradiation with near-infrared rays in a short time by mixing an addition- polymerizable, ethylenically unsaturated compound with a near-infrared polymerization initiator and a hollow filler or thermally expandable microcapsules.
- CONSTITUTION:The composition is prepared by mixing an addition-polymerizable, ethylenically unsaturated compound (e.g. tetramethylolmethane trimethacrylate) with a near-infrared polymerization initiator (e.g. an aniline colorant complex of the formula) and a hollow filler (e.g. 'Shirasu' balloons or thermally expandable microcapsules). Examples of the thermally expandable microcapsule include one prepared by enclosing a low-boiling solvent such as isobutane in a microcapsule of a vinylidene chloride/acrylonitrile copolymer. Because the near-infrared rays can permeate even to the inside of the obtained resin composition when it is irradiated with near-infrared rays, the composition can give an expanded cured product within a short time.
- PN - JP6192459 A 19940712
- PD - 1994-07-12
- ABD - 19941019
- ABV - 018547
- AP - JP19920357728 19921225
- GR - C1262
- PA - THREE BOND CO LTD
- IN - KATSUNO NOBUHIRO
- I - C08J9/14 ;B05D3/06 ;C09K3/10
- SI - C09D4/00